

If the lead lines 15 and 16 are simply inserted into throughholes (not shown) through the printed circuit board 105 in a direction more or less perpendicular to its surface and the CPU 2 with the DC fan 3 is lowered from above after the temperature sensor 11 is fastened to the circuit board 5 (say, by soldering), the lead lines 15 and 16 may fail to bend in the desired direction or be crushed by the vertical downward force. According to a preferred variation to the first embodiment of the invention, as shown generally at 11' in Fig. 3, kinked parts 15a and 16a are provided respectively to the lead lines 15 and 16 where the lead lines 15a and 16a are bent in the same direction in a nearly semi-circular arcuate form, each of the kinked parts 15a and 16a being sandwiched between two mutually colinearly extending portions. The second outer cover 17b according to this embodiment is made somewhat shorter so as not to cover the kinked parts 15a and 16a for the convenience in the operations for mounting the sensor 11' to the printed circuit board 5 by inserting the lead lines 15 and 16 into throughholes 5a provided through the circuit board 5 and soldering them thereto. In other words, the sensor 11' is identical to the sensor 11 described above with reference to Fig. 1.

#### IN THE CLAIMS:

Add the following new claims:

26. A temperature sensor comprising:  
a temperature sensing element having electrodes thereon; and  
elongated electrically conductive lead lines each attached to a corresponding one of said electrodes, said lead lines being elastic, said lead lines each having one end portion attached to a corresponding one of said electrodes and an externally exposed opposite end portion which includes a semicircular kinked part sandwiched between two mutually colinearly extending portions.

27. The temperature sensor of claim 26 wherein said conductive lead lines comprise a material selected from the group consisting of phosphor bronze, german silver, beryllium, SUS, Cu-Ti alloys, brass, plated phosphor bronze, plated german silver, plated beryllium, plated SUS, plated Cu-Ti alloys and plated brass.